Zymet Releases CN-1751-4 Underfill

Written by Chelsey Drysdale Friday, 08 February 2013 11:54 -

CN-1751-4 underfill encapsulant is reportedly crack resistant; withstands flexing experienced by flexible printed circuitry or drops and shocks of thin printed circuit assemblies. Reportedly can withstand deformation without cracking; has a modulus higher than traditional reworkable underfills. Has a CTE of 48 ppm/°C. Viscosity is 900 cps. Can be reworked at 170° to 180°C to remove underfill fillet. Underfill residue is scraped off at 170° to 180°C.

Zymet, www.zymet.com